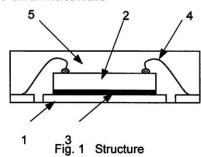


Package: UQFN××SV series

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1.Structure and materials

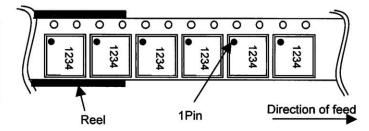


No.	Item	Materials
1	Lead Frame	Cu-Alloy (External lead : Pb free solder plating)
2	Die	Silicon
3	Die Attach	Ag Paste
4	Wire	Au
5	Molding	Epoxy Resin

2. Tape and Reel information

2.1.Packing specification

Таре	Embossed carrier tape
Quantity	See the table on page 4/4
Direction of feed	E2(See Fig. 2)



2.2. Tape and Reel specification

2.2.1. Tape and reel dimensions (See the table on page 5/5)

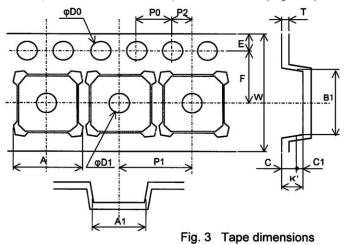


Fig. 2 Typical Tape and Reel configuration

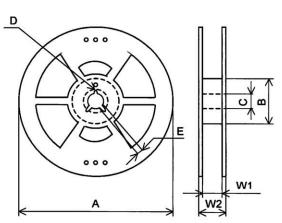


Fig. 4 Reel dimensions

2.3.Leader and Trailer

2.3.1.Leader

No component pockets are 25 pockets or more.

2.3.2.Trailer

No component pockets are 10 pockets or more. Tape is free from reel.

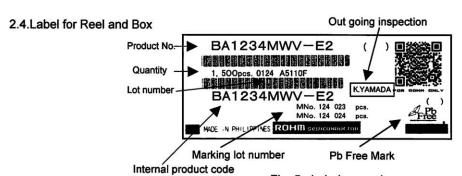
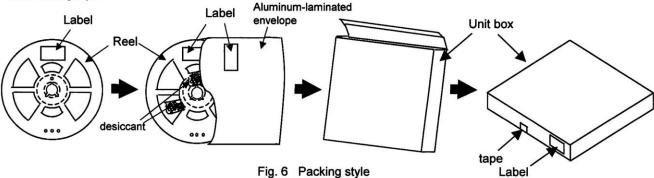


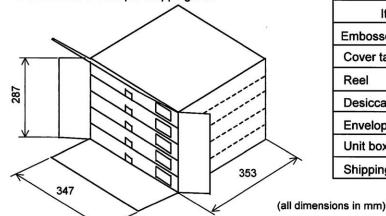
Fig. 5 Label example

2.5.Packing style



2.6. Shipping style

5 unit boxes or less per shipping box



2.7.Packing materials

Item	Material				
Embossed carrier tape	PS				
Cover tape	PET + PE				
Reel	PS				
Desiccant	Silicagel				
Envelope	Aluminume-laminated				
Unit box	Cardboard				
Shipping box	Cardboard				

Fig. 7 Shipping box dimensions and Shipping style

2.8.Others

Cover tape peelback strength is 0.2to0.7N.

Peelback
Peelback speed
300±10mm/min

Fig. 8 Test method

2.8.8.Missing ICs

(1)No consecutive dropouts.

(2)A maximun 0.1% of specified number of products in each packing may be missing.

3.Storage conditions

3.1.Storage environment

Recommended storage conditions are as follows:

-Temperature :5to30°C -Humidity :40to70 RH

3.2.Storage period

-Specified storage period :1year

3.3. Specified storage period until soldering

Dry process before mounting is necessary in the following two case.

- 1. After the package is opened, the product is left unused over 168 hours.
- 2.Before the package is opened, the product is left in the package unused over 1 year.

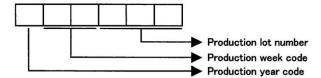
Please excute dry processing in a reel state with 60°C for 72 hours.

At this time, peelback strength of cover tape become 0.2N -0.9N.

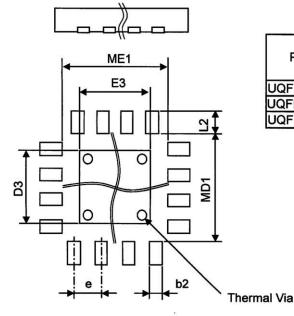
Case of transferring to heatproof container such as trays, excute dry processing with 125°C for 24 hours.

In addition, the dry processing should be max, 2 times due to influence on the product's solderability.

4. Marking lot number



5.Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)



(all	dime	ensior	ne in	mm)
\ an	unit		10 111	

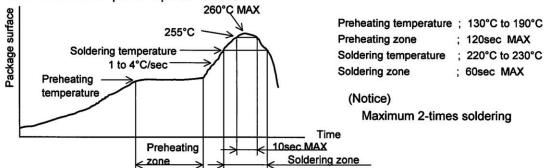
	Land pitch			Land	
Package	Land pitch	spa	ace	width	
	е	MD1	ME1	L2	b 2
UQFN56SV7070	0.40	5.60	5.60	1.00	0.22
UQFN64SAV080	0.40	6.60	6.60	1.00	0.22
UQFN88SV0100	0.40	8.80	8.80	0.90	0.22

	Radiation	on land	Thermal Via			
Package	length	width				
	D3	E3	Pitch	Diameter		
UQFN56SV7070	4.60	4.60	1.20	φ0.300		
UQFN64SAV080	3.70	3.70	1.20	φ0.300		
UQFN88SV0100	7.80	7.80	1.20	φ0.300		

^{*}The lead toe and lead side fillet may not be achieved because of non-lead packages.

6. Soldering conditions

6.1.Recommended temperature profile for reflow

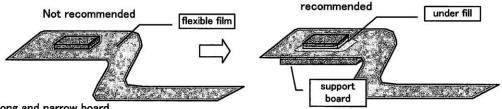


6.2. The wave soldering method is not supported.

6.3 Notice information of board mounting

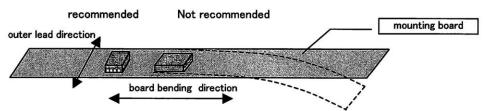
Mounting on flexible film

Mounting on flexible film, film bend may occur lack of lead from package, usage of support board and under fill is recommended.

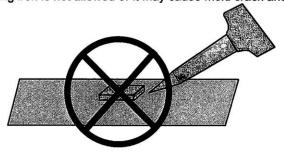


Mounting on long and narrow board

Mounting on long and narrow board, bending stress may occur a luck of lead from package, bending board direction and outer lead direction is recommended as drawing (vertically layout) and under fill usage is recommended.



6.4 Rework by solering iron is not allowed or it may cause mold crack and terminal open.



(Tape dimensions)

Package	Quantity			Tape dimensions (all dimensions in mm)											
Package	(pcs)	A1	B1	С	C1	D0	D1	E	F	K'	P0	P1	P2	T	W
UQFN56SV7070	1500	7.2	7.2	(1.15)	(0.65)	φ1.5	φ1.5	1.75	7.5	1.80	4.0	12.0	2.0	0.3	16.0
UQFN64SAV080	1000	8.2	8.2	(1.15)	(0.65)	φ1.5	φ1.5	1.75	7.5	1.8	4.0	12.0	2.0	0.3	16.0
UQFN88SV0100	1000	10.2	10.2	1.15	0.70	φ1.5	φ1.5	1.75	7.5	1.85	4.0	12.0	2.0	0.3	16.0
Tolera	nce	±0.05	±0.05	•	-	+0.1/0	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.05	±0.3

(Reel dimensions)

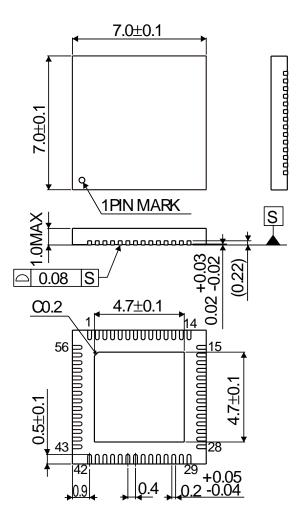
<Dehydrated weight >

Package	Ree	el dime	nsions	Dehydrated weight				
Fackage	Α	В	С	D	Е	W1	W2	(g)
UQFN56SV7070	φ330	φ80	φ13.0	φ20.2	1.5	17.4	21.4	0.129
UQFN64SAV080	φ330	φ80	φ13.0	φ20.2	1.5	17.4	21.4	0.155
UQFN88SV0100	φ330	φ50	φ13.0	φ20.2	1.5	17.4	21.4	0.236
Tolerance	-	+1.0/0	±0.2	MIN	MIN	+1.0/0	±1.0	



Package Dimensions

UQFN56SV7070



(Unit: mm)

Notes

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